Data Sheet FN3150.5

Single 16 and 8, Differential 8-Channel and 4-Channel CMOS Analog MUXs with Active Overvoltage Protection

The HI-546, HI-547, HI-548 and HI-549 are analog multiplexers with active overvoltage protection and guaranteed r_{ON} matching. Analog input levels may greatly exceed either power supply without damaging the device or disturbing the signal path of other channels. Active protection circuitry assures that signal fidelity is maintained even under fault conditions that would destroy other multiplexers.

Analog inputs can withstand constant $70V_{P-P}$ levels with ±15V supplies. Digital inputs will also sustain continuous faults up to 4V greater than either supply. In addition, signal sources are protected from short circuiting should multiplexer supply loss occur. Each input presents 1kΩ of resistance under this condition. These features make the HI-546, HI-547, HI-548 and HI-549 ideal for use in systems where the analog inputs originate from external equipment or separately powered circuitry. All devices are fabricated with 44V Dielectrically Isolated CMOS technology. The HI-546 is a single 16-Channel, the HI-547 is an 8-Channel differential, the HI-548 is a single 8-Channel and the HI-549 is a 4-Channel differential device. If input overvoltage protection is not needed the HI-506/507/508/509 multiplexers are recommended. For further information see Application Notes AN520 and AN521.

For MIL-STD-883 compliant parts, request the HI-546/883, HI-547/883, HI-548/883 and HI-549/883 datasheets.

Features

- Analog Overvoltage Protection. . . . . $70V_{P-P}$
- No Channel Interaction During Overvoltage
- Guaranteed r_{ON} Matching
- Maximum Power Supply. 44V
- Break-Before-Make Switching
- Analog Signal Range . . . . . ±15V
- Access Time (Typical) 500ns
- Standby Power (Typical). 7.5mW
- Pb-Free Plus Anneal Available (RoHS Compliant)

Applications

- Data Acquisition
- Industrial Controls
- Telemetry

Ordering Information

PART NUMBER	PART MARKING	TEMP. RANGE (^{o}C)	PACKAGE	PKG. DWG. #
HI1-0546-5	HI1-546-5	0 to 75	28 Ld CERDIP	F28.6
HI1-0546-2	HI1-546-2	-55 to 125	28 Ld CERDIP	F28.6
HI3-0546-5	HI3-546-5	0 to 75	28 Ld PDIP	E28.6
HI4P0546-5	HI4P546-5	0 to 75	28 Ld PLCC	N28.45
HI4P0546-5Z (Note)	HI4P546-5Z	0 to 75	28 Ld PLCC (Pb-free)	N28.45
HI9P0546-9**	HI9P546-9	-40 to 85	28 Ld SOIC	M28.3
HI9P0546-9Z** (Note)	HI9P546-9Z	-40 to 85	28 Ld SOIC (Pb-free)	M28.3
HI1-0547-5	HI1-547-5	0 to 75	28 Ld CERDIP	F28.6
HI3-0547-5	HI3-547-5	0 to 75	28 Ld PDIP	E28.6
HI3-0547-5Z (Note)	HI3-0547-5Z	0 to 75	28 Ld PDIP* (Pb-free)	E28.6
HI4P0547-5	HI4P547-5	0 to 75	28 Ld PLCC	N28.45
HI4P0547-5Z (Note)	HI4P547-5Z	0 to 75	28 Ld PLCC (Pb-free)	N28.45
HI9P0547-9	HI9P547-9	-40 to 85	28 Ld SOIC	M28.3
HI9P0547-9Z (Note)	HI9P547-9Z	-40 to 85	28 Ld SOIC (Pb-free)	M28.3
HI1-0548-2	HI1-548-2	-55 to 125	16 Ld CERDIP	F16.3
HI1-0548-5	HI1-548-5	0 to 75	16 Ld CERDIP	F16.3
HI3-0548-5	HI3-548-5	0 to 75	16 Ld PDIP	E16.3
HI4P0548-5	HI4P548-5	0 to 75	20 Ld PLCC	N20.35

Ordering Information (Continued)

PART NUMBER	PART MARKING	TEMP. RANGE (^{o}C)	PACKAGE	PKG. DWG. #
HI9P0548-5**	HI9P548-5	0 to 75	16 Ld SOIC	M16.15
HI9P0548-5Z** (Note)	HI9P548-5Z	0 to 75	16 Ld SOIC (Pb-free)	M16.15
HI9P0548-9	HI9P548-9	-40 to 85	16 Ld SOIC	M16.15
HI9P0548-9Z (Note)	HI9P548-9Z	-40 to 85	16 Ld SOIC (Pb-free)	M16.15
HI1-0549-2	HI1-549-2	-55 to 125	16 Ld CERDIP	F16.3
HI3-0549-5	HI3-549-5	0 to 75	16 Ld PDIP	E16.3
HI4P0549-5	HI4P549-5	0 to 75	20 Ld PLCC	N20.35
HI4P0549-5Z (Note)	HI4P549-5Z	0 to 75	20 Ld PLCC (Pb-free)	N20.35
HI9P0549-9	HI9P549-9	-40 to 85	16 Ld SOIC	M16.15
HI9P0549-9Z (Note)	HI9P549-9Z	-40 to 85	16 Ld SOIC (Pb-free)	M16.15

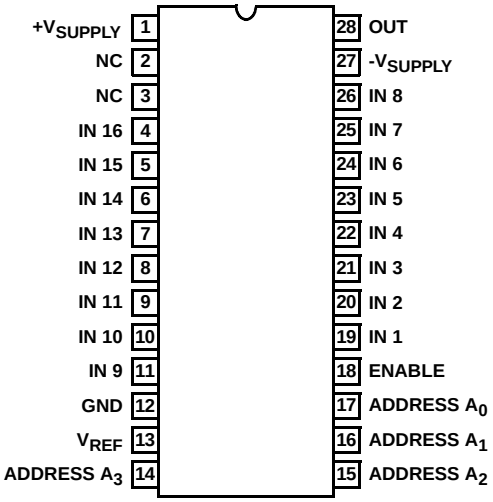
*Pb-free PDIPs can be used for through hole wave solder processing only. They are not intended for use in Reflow solder processing applications.

**Add “96” suffix for tape and reel.

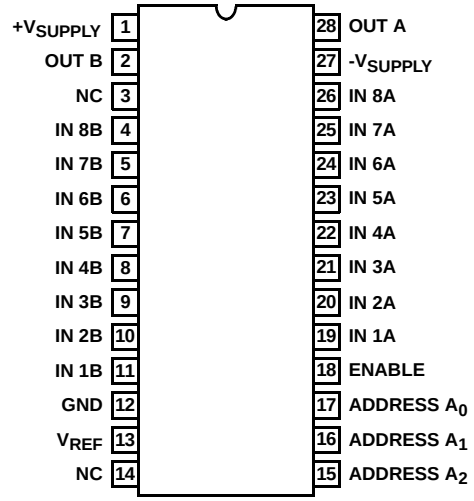
NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Pinouts

HI-546 (CERDIP, PDIP, SOIC)
TOP VIEW



HI-547 (CERDIP, PDIP, SOIC)
TOP VIEW



Absolute Maximum Ratings

V+ to V- . . . . . +44V
V+ to GND . . . . . +22V
V- to GND. . . . . -25V
Digital Input Voltage (V_{EN}, V_A) . . . . . (V-) -4V to (V+) +4V
Analog Signal (V_{IN}, V_{OUT}). . . . . (V-) -20V to (V+) +20V
or 20mA, Whichever Occurs First
Continuous Current, IN or OUT 20mA
Peak Current, IN or OUT (Pulsed 1ms, 10% Duty Cycle Max) . . 40mA

Operating Conditions

Temperature Ranges
HI-546/548/549-2 . . . . . -55^oC to 125^oC
HI-546/547/548/549-5 . . . . . 0^oC to 75^oC
HI-546/547/548/549-9 . . . . . -40^oC to 85^oC

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} ($^oC/W$)	θ_{JC} ($^oC/W$)
16 Ld CERDIP Package	85	32
28 Ld CERDIP Package	55	18
28 Ld PDIP Package*	60	N/A
16 Ld PDIP Package	90	N/A
28 Ld PLCC Package	70	N/A
20 Ld PLCC Package	80	N/A
28 Ld SOIC Package	75	N/A
16 Ld SOIC Package	105	N/A

Maximum Junction Temperature
Ceramic Packages . . . . . 175^oC
Plastic Packages . . . . . 150^oC
Maximum Storage Temperature Range. . . . . -65^oC to 150^oC
Maximum Lead Temperature (Soldering 10s) . . . . . 300^oC
(PLCC, SOIC - Lead Tips Only)
*Pb-free PDIPs can be used for through hole wave solder processing only. They are not intended for use in Reflow solder processing applications.

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications

Supplies = +15V, -15V; V_{REF} Pin = Open; V_{AH} (Logic Level High) = 4V; V_{AL} (Logic Level Low) = 0.8V; Unless Otherwise Specified. For Test Conditions, Consult Test Circuits Section

PARAMETER	TEST CONDITIONS	TEMP (^oC)	-2			-5, -9			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
SWITCHING CHARACTERISTICS									
Access Time, t_A		25	-	0.5	-	-	0.5	-	µs
		Full	-	-	1.0	-	-	1.0	µs
Break-Before Make Delay, t_{OPEN}		25	25	80	-	25	80	-	ns
Enable Delay (ON), $t_{ON(EN)}$		25	-	300	500	-	300	-	ns
		Full	-	-	1000	-	-	1000	ns
Enable Delay (OFF), $t_{OFF(EN)}$		25	-	300	500	-	300	-	ns
		Full	-	-	1000	-	-	1000	ns
Settling Time	To 0.1%	25	-	1.2	-	-	1.2	-	µs
	To 0.01%	25	-	3.5	-	-	3.5	-	µs
Off Isolation	Note 6	25	50	68	-	50	68	-	dB
Channel Input Capacitance, $C_{S(OFF)}$		25	-	10	-	-	10	-	pF
Channel Output Capacitance $C_{D(OFF)}$									
HI-546		25	-	52	-	-	52	-	pF
HI-547		25	-	30	-	-	30	-	pF
HI-548		25	-	25	-	-	25	-	pF
HI-549		25	-	12	-	-	12	-	pF
Input to Output Capacitance, $C_{DS(OFF)}$		25	-	0.1	-	-	0.1	-	pF
DIGITAL INPUT CHARACTERISTICS									
Input Low Threshold, TTL Drive, V_{AL}		Full	-	-	0.8	-	-	0.8	V
Input High Threshold, V_{AH} (Note 8)		Full	4.0	-	-	4.0	-	-	V
MOS Drive, V_{AL} (HI-546/547 Only)	V_{REF} = 10V	25	-	-	0.8	-	-	0.8	V

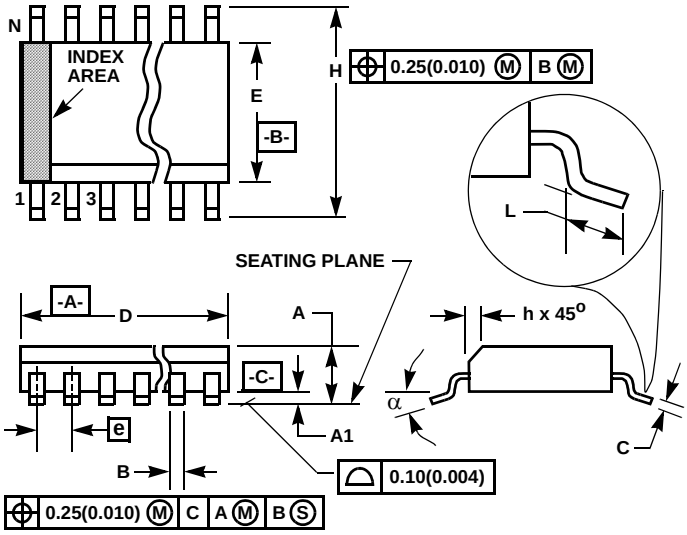
Electrical Specifications Supplies = +15V, -15V; V_{REF} Pin = Open; V_{AH} (Logic Level High) = 4V; V_{AL} (Logic Level Low) = 0.8V; Unless Otherwise Specified. For Test Conditions, Consult Test Circuits Section **(Continued)**

PARAMETER	TEST CONDITIONS	TEMP (^{O}C)	-2			-5, -9			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
MOS Drive, V_{AH} (HI-546/547 Only)	V_{REF} = 10V	25	6.0	-	-	6.0	-	-	V
Input Leakage Current (High or Low), I_A	Note 5	Full	-	-	1.0	-	-	1.0	µA
ANALOG CHANNEL CHARACTERISTICS									
Analog Signal Range, V_{IN}		Full	-15	-	+15	-15	-	+15	V
On Resistance, r_{ON}	Note 2	25	-	1.2	1.5	-	1.5	1.8	kΩ
		Full	-	1.5	1.8	-	1.8	2.0	kΩ
Δr_{ON}, (Any Two Channels)		25	-	-	7.0	-	-	7.0	%
Off Input Leakage Current, $I_{S(OFF)}$	Note 3	25	-	0.03	-	-	0.03	-	nA
		Full	-	-	50	-	-	50	nA
Off Output Leakage Current, $I_{D(OFF)}$	Note 3	25	-	0.1	-	-	0.1	-	nA
HI-546		Full	-	-	300	-	-	300	nA
HI-547		Full	-	-	200	-	-	200	nA
HI-548		Full	-	-	200	-	-	200	nA
HI-549		Full	-	-	100	-	-	100	nA
$I_{D(OFF)}$ With Input Overvoltage Applied	Note 4	25	-	4.0	-	-	4.0	-	nA
		Full	-	-	2.0	-	-	-	µA
On Channel Leakage Current, $I_{D(ON)}$	Note 3	25	-	0.1	-	-	0.1	-	nA
HI-546		Full	-	-	300	-	-	300	nA
HI-547		Full	-	-	200	-	-	200	nA
HI-548		Full	-	-	200	-	-	200	nA
HI-549		Full	-	-	100	-	-	100	nA
Differential Off Output Leakage Current I_{DIFF} (HI-547, HI-549 Only)		Full	-	-	50	-	-	50	nA
POWER SUPPLY CHARACTERISTICS									
Power Dissipation, P_D		Full	-	7.5	-	-	7.5	-	mW
Current, I+	Note 7	Full	-	0.5	2.0	-	0.5	2.0	mA
Current, I-	Note 7	Full	-	0.02	1.0	-	0.02	1.0	mA

NOTES:

2. V_{OUT} = ±10V, I_{OUT} = ∓100µA.
3. 10nA is the practical lower limit for high speed measurement in the production test environments.
4. Analog Overvoltage = ±33V.
5. Digital input leakage is primarily due to the clamp diodes (see Schematic). Typical leakage is less than 1nA at 25^{O}C.
6. V_{EN} = 0.8V, R_L = 1K, C_L = 15pF, V_S = 7V_{RMS}, f = 100kHz.
7. V_{EN}, V_A = 0V or 4V.
8. To drive from DTL/TTLCircuits, 1kΩ pull-up resistors to +5V supply are recommended.

Small Outline Plastic Packages (SOIC)



NOTES:

1. Symbols are defined in the “MO Series Symbol List” in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension “D” does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension “E” does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. “L” is the length of terminal for soldering to a substrate.
7. “N” is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width “B”, as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M28.3 (JEDEC MS-013-AE ISSUE C)
28 LEAD WIDE BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0926	0.1043	2.35	2.65	-
A1	0.0040	0.0118	0.10	0.30	-
B	0.013	0.0200	0.33	0.51	9
C	0.0091	0.0125	0.23	0.32	-
D	0.6969	0.7125	17.70	18.10	3
E	0.2914	0.2992	7.40	7.60	4
e	0.05 BSC		1.27 BSC		-
H	0.394	0.419	10.00	10.65	-
h	0.01	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	28		28		7
α	0^o	8^o	0^o	8^o	-